

## FEATURES

- | Planar Die Construction

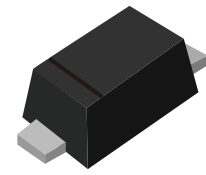
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- | 150mW Power Dissipation

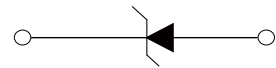
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- | Zener Voltages from 2.4 – 43V

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SOD-523



Schematic Symbol

## APPROVALS

<b>RoHS</b>	Compliance with 2011/65/EU
<b>HF</b>	Compliance with IEC61249-2-21:2003

## MAXIMUM RATINGS ( $T_A=25^{\circ}\text{C}$ )

Parameter	Symbo	Value	Unit
Power Dissipation	$P_D$	150	mW
Maximum forward voltage at $I_F=10\text{mA}$	$V_F$	0.9	V
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	833	$^{\circ}\text{C}/\text{W}$
Storage temperature range	$T_J, T_{STG}$	-55 to +150	$^{\circ}\text{C}$

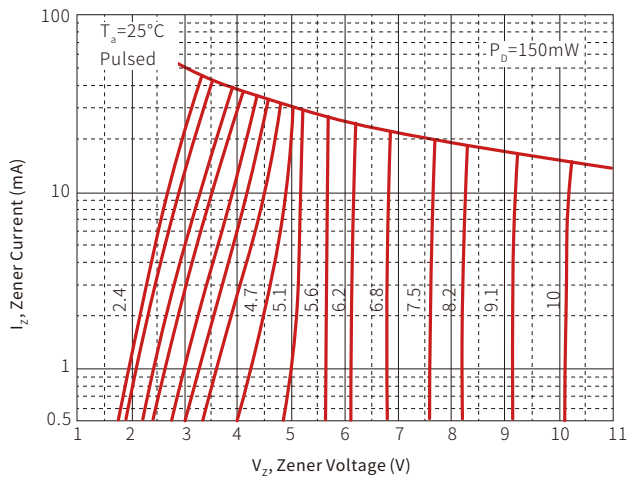
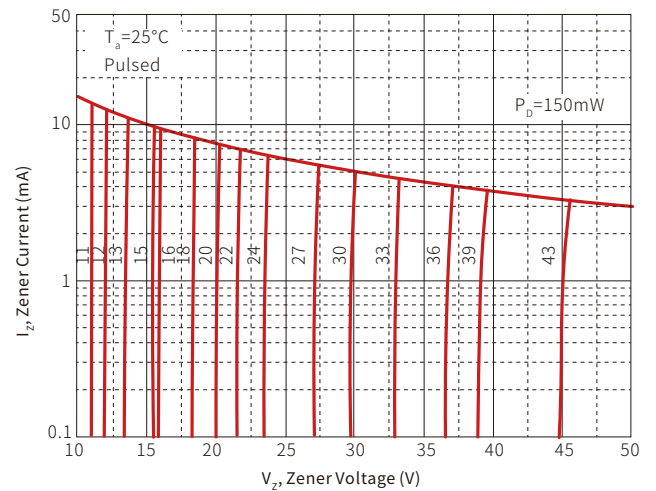
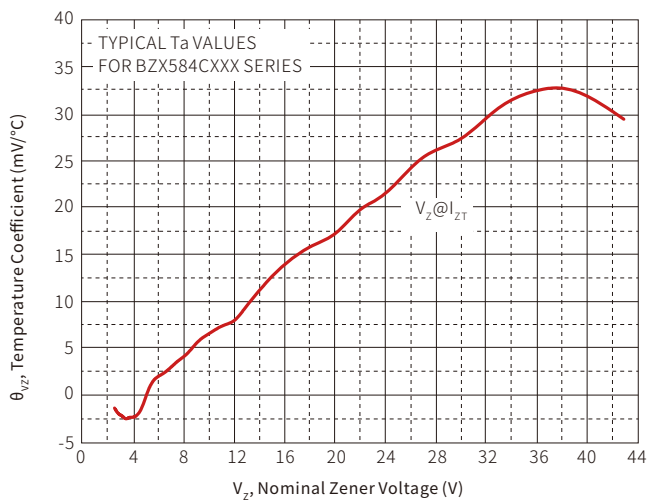
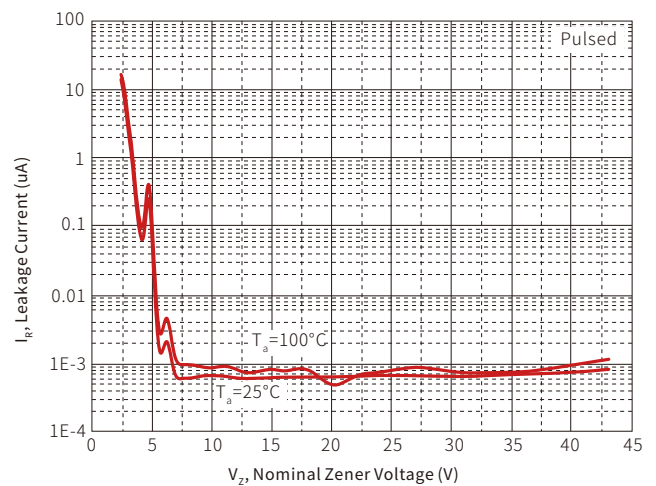
# ELECTRICAL CHARACTERISTICS

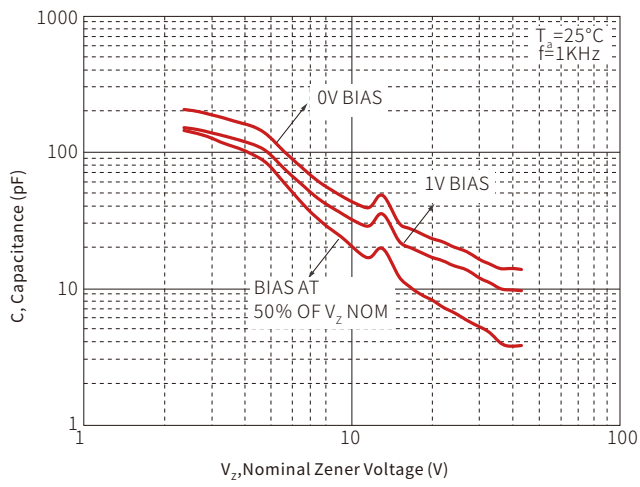
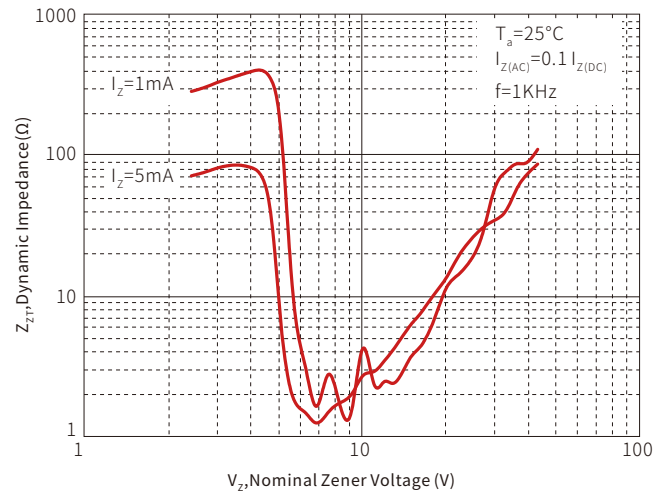
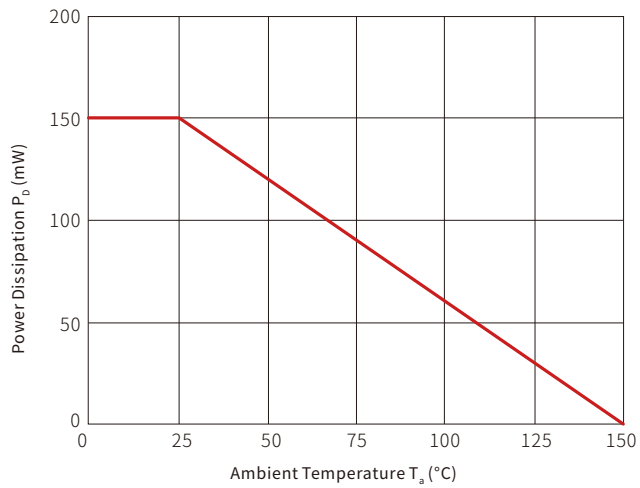
Part Number	Device Marking Code	Zener Voltage Range (Note 1)				Maximum Zener Impedance (Note 2)			Maximum Reverse Current		Typical temperature coefficient @ $I_{ZT}$ mV/°C	
		$V_Z@I_{ZT}$			$I_{ZT}$	$Z_{ZT}@I_{ZT}$	$Z_{ZK}@I_{ZK}$		$I_R$	$V_R$	Min	Max
		Nom(V)	Min(V)	Max(V)	(mA)	( $\Omega$ )	(mA)	( $\mu$ A)	(V)			
BZX584C2V4	Z11	2.4	2.20	2.60	5	100	600	1.0	50	1.0	-3.5	0
BZX584C2V7	Z12	2.7	2.5	2.9	5	100	600	1.0	20	1.0	-3.5	0
BZX584C3V0	Z13	3.0	2.8	3.2	5	95	600	1.0	10	1.0	-3.5	0
BZX584C3V3	Z14	3.3	3.1	3.5	5	95	600	1.0	5	1.0	-3.5	0
BZX584C3V6	Z15	3.6	3.4	3.8	5	90	600	1.0	5	1.0	-3.5	0
BZX584C3V9	Z16	3.9	3.7	4.1	5	90	600	1.0	3	1.0	-3.5	0
BZX584C4V3	Z17	4.3	4.0	4.6	5	90	600	1.0	3	1.0	-3.5	0
BZX584C4V7	Z1	4.7	4.4	5.0	5	80	500	1.0	3	2.0	-3.5	0.2
BZX584C5V1	Z2	5.1	4.8	5.4	5	60	480	1.0	2	2.0	-2.7	1.2
BZX584C5V6	Z3	5.6	5.2	6.0	5	40	400	1.0	1	2.0	-2.0	2.5
BZX584C6V2	Z4	6.2	5.8	6.6	5	10	150	1.0	3	4.0	0.4	3.7
BZX584C6V8	Z5	6.8	6.4	7.2	5	15	80	1.0	2	4.0	1.2	4.5
BZX584C7V5	Z6	7.5	7.0	7.9	5	15	80	1.0	1	5.0	2.5	5.3
BZX584C8V2	Z7	8.2	7.7	8.7	5	15	80	1.0	0.7	5.0	3.2	6.2
BZX584C9V1	Z8	9.1	8.5	9.6	5	15	100	1.0	0.5	6.0	3.8	7.0
BZX584C10	Z9	10	9.4	10.6	5	20	150	1.0	0.2	7.0	4.5	8.0
BZX584C11	Y1	11	10.4	11.6	5	20	150	1.0	0.1	8.0	5.4	9.0
BZX584C12	Y2	12	11.4	12.7	5	25	150	1.0	0.1	8.0	6.0	10.0
BZX584C13	Y3	13	12.4	14.1	5	30	170	1.0	0.1	8.0	7.0	11.0
BZX584C15	Y4	15	13.8	15.6	5	30	200	1.0	0.1	10.5	9.2	13.0
BZX584C16	Y5	16	15.3	17.1	5	40	200	1.0	0.1	11.2	10.4	14.0
BZX584C18	Y6	18	16.8	19.1	5	45	225	1.0	0.1	12.6	12.4	16.0
BZX584C20	Y7	20	18.8	21.2	5	55	225	1.0	0.1	14.0	14.4	18.0
BZX584C22	Y8	22	20.8	23.3	5	55	250	1.0	0.1	15.4	16.4	20.0
BZX584C24	Y9	24	22.8	25.6	5	70	250	1.0	0.1	16.8	18.4	22.0
BZX584C27	Y10	27	25.1	28.9	2	80	300	0.5	0.1	18.9	21.4	25.3
BZX584C30	Y11	30	28.0	32.0	2	80	300	0.5	0.1	21.0	24.4	29.4
BZX584C33	Y12	33	31.0	35.0	2	80	325	0.5	0.1	23.1	27.4	33.4
BZX584C36	Y13	36	34.0	38.0	2	90	350	0.5	0.1	25.2	30.4	37.4
BZX584C39	Y14	39	37.0	41.0	2	130	350	0.5	0.1	27.3	33.4	41.2
BZX584C43	Y15	43	40.0	46.0	2	100	700	1.0	0.1	32.0	10.0	12.0

**Notes:**

1. Tested with pulses, period=5ms, pulse width =300 $\mu$ s.
2. f = 1 kHz

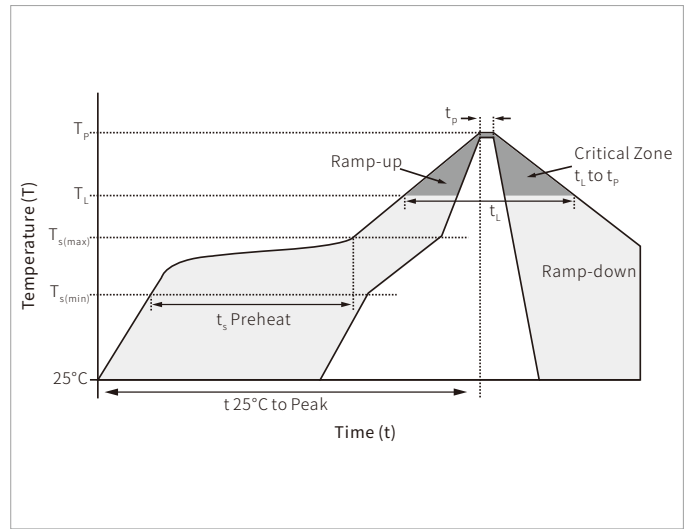
# CHARACTERISTIC CURVES

**Zener Characteristics ( $V_z$  Up to 10 V)**

**Zener Characteristics (11 V to 43 V)**

**Temperature Coefficients**

**Typical Leakage Current**


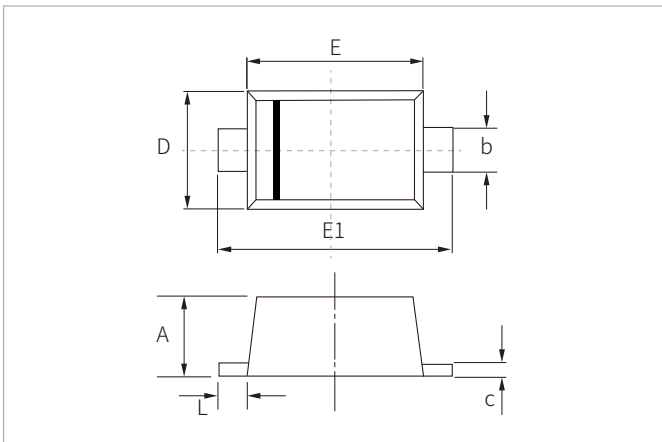
**Typical Capacitance**

**Effect of Zener Voltage on Zener Impedance**

**Power Derating Curve**


## SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ( $T_{s(min)}$ )	150°C
	Temperature Max ( $T_{s(max)}$ )	200°C
	Time (min to max) ( $t_s$ )	60 – 180 secs
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak)		3°C/second max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/second max
Reflow	Temperature ( $T_L$ ) (Liquidus)	217°C
	Time (min to max) ( $t_L$ )	60 – 150 seconds
Peak Temperature ( $T_p$ )		260°C
Time within 5°C of actual peak Temperature ( $t_p$ )		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature ( $T_p$ )		8 minutes max.
Do not exceed		260°C

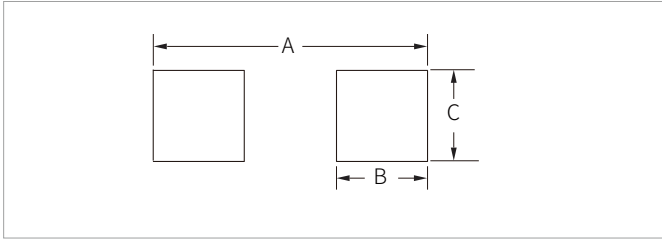


## SOD-523 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.50	0.80	0.020	0.031
b	0.25	0.35	0.010	0.014
c	0.07	0.20	0.003	0.008
D	0.70	0.90	0.028	0.035
E	1.10	1.30	0.043	0.051
E1	1.50	1.70	0.059	0.067
L	0.15	0.25	0.006	0.010

## RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters	Inches
	Min.	Min.
A	2.00	0.0787
B	0.60	0.0236
C	0.70	0.0276

## ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
BZX584C2V4-BZX584C43	SOD-523	3000PCS	7"

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